SN75451B, SN75452B, SN75453B, SN55454B SN75451B, SN75452B, SN75453B, SN75454B DUAL PERIPHERAL DRIVERS

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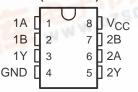
PERIPHERAL DRIVERS FOR HIGH-CURRENT SWITCHING AT VERY HIGH SPEEDS

- Characterized for Use to 300 mA
- High-Voltage Outputs
- No Output Latch-Up at 20 V (After Conducting 300 mA)
- High-Speed Switching
- Circuit Flexibility for Varied Applications
- TTL-Compatible Diode-Clamped Inputs
- Standard Supply Voltages
- Plastic DIP (P) With Copper Lead Frame Provides Cooler Operation and Improved Reliability
- Package Options Include Plastic Small-Outline Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs

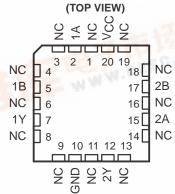
SUMMARY OF DEVICES

	DEVICE	LOGIC OF	PACKAGES
1	SN55451B	AND	FK, JG
	SN55452B	NAND	JG
ı	SN55453B	OR	FK, JG
I	SN55454B	NOR	JG
I	SN75451B	AND	D, P
ı	SN75452B	NAND	D, P
ı	SN75453B	OR	D, P
ı	SN75454B	NOR	D, P

SN55451B, SN55452B, SN55453B, SN55454B . . . JG PACKAGE SN75451B, SN75452B, SN75453B, SN75454B . . . D OR P PACKAGE (TOP VIEW)



SN55451B, SN55452B SN55453B, SN55454B . . . FK PACKAGE



NC - No internal connection

description

The SN55451B through SN55454B and SN75451B through SN75454B are dual peripheral drivers designed for use in systems that employ TTL logic. This family is functionally interchangeable with and replaces the SN75450 family and the SN75450A family devices manufactured previously. The speed of the devices is equal to that of the SN75450 family, and the parts are designed to ensure freedom from latch-up. Diode-clamped inputs simplify circuit design. Typical applications include high-speed logic buffers, power drivers, relay drivers, lamp drivers, MOS drivers, line drivers, and memory drivers.

The SN55451B/SN75451B, SN55452B/SN75452B, SN55453B/SN75453B, and SN55454B/SN75454B are dual peripheral AND, NAND, OR, and NOR drivers, respectively (assuming positive logic), with the output of the logic gates internally connected to the bases of the npn output transistors.

The SN55' drivers are characterized for operation over the full military range of -55°C to 125°C. The SN75' drivers are characterized for operation from 0°C to 70°C.



SN55451B, SN55452B, SN55453B, SN55454B SN75451B, SN75452B, SN75453B, SN75454B DUAL PERIPHERAL DRIVERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

		SN55'	SN75'	UNIT
Supply voltage, V _{CC} (see Note 1)		7	7	V
Input voltage, V _I	5.5	5.5	V	
Inter-emitter voltage (see Note 2)	5.5	5.5	V	
Off-state output voltage, VO	30	30	V	
Continuous collector or output current, I _{OK} (see Note 3)	400	400	mA	
Peak collector or output current, I_I ($t_W \le 10$ ms, duty cycle $\le 50\%$, se	500	500	mA	
Continuous total power dissipation		See Dissipation Rating Table		
Operating free-air temperature range, TA		-55 to 125	0 to 70	°C
Storage temperature range, T _{Stg}		-65 to 150	-65 to 150	°C
Case temperature for 60 seconds	FK package			°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds	n case for 60 seconds			°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	D or P package		260	°C

NOTES: 1. Voltage values are with respect to network GND, unless otherwise specified.

- 2. This is the voltage between two emitters of a multiple-emitter transistor.
- 3. This value applies when the base-emitter resistance (RBE) is equal to or less than 500 Ω .
- 4. Both halves of these dual circuits may conduct rated current simultaneously; however, power dissipation averaged over a short time interval must fall within the continuous dissipation rating.

DISSIPATION RATING TABLE

PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 125°C POWER RATING
D	725 mW	5.8 mW/°C	464 mW	_
FK	1375 mW	11.0 mW/°C	880 mW	275 mW
JG	1050 mW	8.4 mW/°C	672 mW	210 mW
Р	1000 mW	8.0 mW/°C	640 mW	_

recommended operating conditions

	SN55'			SN75'			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level input voltage, V _{IH}	2			2			V
Low-level input voltage, V _{IL}			0.8			0.8	V
Operating free-air temperature, TA	-55		125	0		70	°C



logic symbol†

1A $\frac{1}{2}$ & \bigcirc 1Y 2A $\frac{6}{7}$ 2S \bigcirc 2Y

† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC publication 617-12.

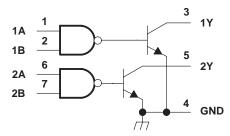
Pin numbers shown are for the D, JG, and P packages.

FUNCTION TABLE (each driver)

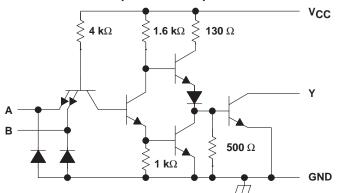
Α	В	Υ
L	L	L (on state)
L	Н	L (on state)
Н	L	L (on state)
Н	Н	H (off state)

positive logic: Y = AB or A+B

logic diagram (positive logic)



schematic (each driver)



Resistor values shown are nominal.

electrical characteristics over recommended operating free-air temperature range

	PARAMETER	TEST 001	DITIONST	S	N55451E	3	SN75451B			UNIT
	PARAMETER	TEST CONDITIONS‡		MIN	TYP§	MAX	MIN	TYP§	MAX	UNII
VIK	Input clamp voltage	$V_{CC} = MIN,$	$I_{I} = -12 \text{ mA}$		-1.2	-1.5		-1.2	-1.5	V
V	Low-level output voltage	V _{CC} = MIN, I _{OL} = 100 mA	$V_{IL} = 0.8 V,$		0.25	0.5		0.25	0.4	
VOL		V _{CC} = MIN, I _{OL} = 300 mA	V _{IL} = 0.8 V,		0.5	0.8		0.5	0.7	V
ЮН	High-level output current	V _{CC} = MIN, V _{OH} = 30 V	V _{IH} = MIN,			300			100	μΑ
lį	Input current at maximum input voltage	$V_{CC} = MAX$,	V _I = 5.5 V			1			1	mA
ΊΗ	High-level input current	$V_{CC} = MAX$,	V _I = 2.4 V			40			40	μΑ
Ι _Ι L	Low-level input current	$V_{CC} = MAX$,	V _I = 0.4 V		-1	-1.6		-1	-1.6	mA
ІССН	Supply current, outputs high	$V_{CC} = MAX$,	V _I = 5 V		7	11		7	11	mA
ICCL	Supply current, outputs low	$V_{CC} = MAX,$	V _I = 0		52	65		52	65	mA

[‡] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. § All typical values are at V_{CC} = 5 V, T_A = 25°C.

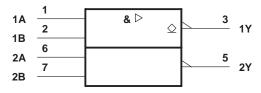
switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER			TEST CONDITIONS			MAX	UNIT
^t PLH	Propagation delay time, low-to-high-level	output				18	25	
tPHL	Propagation delay time, high-to-low-level	output	I _O ≈ 200 mA,	$C_L = 15 pF$,		18	25	no
tTLH	Transition time, low-to-high-level output	ansition time, low-to-high-level output		See Figure 1		5	8	ns
tTHL	Transition time, high-to-low-level output	gh-to-low-level output				7	12	
\/a	High-level output voltage after switching	SN55451B	V _S = 20 V, See Figure 2	I _O ≈ 300 mA,		V _S -6.5		mV
VOH		SN75451B		-	V _S −6.5			l IIIV



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logic symbol[†]



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC publication 617-12.

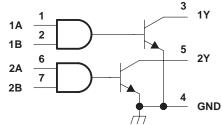
Pin numbers shown are for the D, JG, and P packages.

FUNCTION TABLE (each driver)

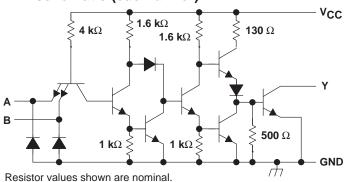
Α	В	Υ
L	L	H (off state)
L	Н	H (off state)
Н	L	H (off state)
Н	Н	L (on state)

positive logic: $Y = \overline{AB}$ or $\overline{A+B}$

logic diagram (positive logic)



schematic (each driver)



electrical characteristics over recommended operating free-air temperature range

	PARAMETER	TEOT 001	IDITIONS [†]		SN55452E	3	SN75452B			UNIT
	PARAMETER	TEST CONDITIONS [‡]		MIN	TYP§	MAX	MIN	TYP§	MAX	UNII
VIK	Input clamp voltage	$V_{CC} = MIN,$	$I_1 = -12 \text{ mA}$		-1.2	-1.5		-1.2	-1.5	V
\/-·	Low level output voltage	$V_{CC} = MIN,$ $I_{OL} = 100 \text{ mA}$	$V_{IH} = MIN,$		0.25	0.5		0.25	0.4	٧
VOL	Low-level output voltage	$V_{CC} = MIN,$ $I_{OL} = 300 \text{ mA}$	V _{IH} = MIN,		0.5	0.8		0.5	0.7	V
ЮН	High-level output current	V _{CC} = MIN, V _{OH} = 30 V	V _{IL} = 0.8 V,			300			100	μΑ
lį	Input current at maximum input voltage	$V_{CC} = MAX$,	V _I = 5.5 V			1			1	mA
ΙΗ	High-level input current	$V_{CC} = MAX$,	V _I = 2.4 V			40			40	μΑ
Ι _Ι L	Low-level input current	$V_{CC} = MAX$,	V _I = 0.4 V		-1.1	-1.6		-1.1	-1.6	mA
ICCH	Supply current, outputs high	$V_{CC} = MAX$,	V _I = 0		11	14		11	14	mA
ICCL	Supply current, outputs low	$V_{CC} = MAX$,	V _I = 5 V		56	71	·	56	71	mA

[‡] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER			TEST CONDITIONS			MAX	UNIT
tPLH	Propagation delay time, low-to-high-level output					26	35	
tPHL	Propagation delay time, high-to-low-level output		I _O ≈ 200 mA,	$C_L = 15 pF$,		24	35	
tTLH	Transition time, low-to-high-level output	-to-high-level output		See Figure 1		5	8	ns
tTHL	Transition time, high-to-low-level output					7	12	
Va	High level extent valte as after exitation	SN55452B	Vs = 20 V,	I _O ≈ 300 mA,		Vs-6.5		mV
VOH	High-level output voltage after switching	SN75452B	See Figure 2	-	V _S −6.5			IIIV



 $[\]S$ All typical values are at $V_{CC} = 5$ V, $T_A = 25$ °C.

logic symbol†

†This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC publication 617-12.

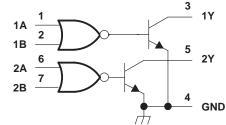
Pin numbers shown are for the D, JG, and P packages.

FUNCTION TABLE (each driver)

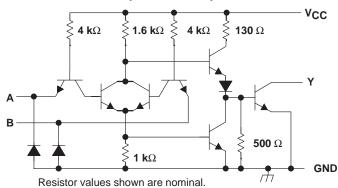
Α	В	Y
L	L	L (on state)
L	Н	H (off state)
Н	L	H (off state)
Н	Н	H (off state)

positive logic: $\underline{\underline{}}$ Y = A+B or \overline{A} \overline{B}

logic diagram (positive logic)



schematic (each driver)



electrical characteristics over recommended operating free-air temperature range

	DADAMETED		DITIONS [†]	5	N55453E	3	SN75453B			UNIT
	PARAMETER	TEST CONDITIONS‡		MIN	TYP§	MAX	MIN	TYP§	MAX	UNII
VIK	Input clamp voltage	$V_{CC} = MIN,$	$I_{I} = -12 \text{ mA}$		-1.2	-1.5		-1.2	-1.5	V
V	Low lovel output voltage	$V_{CC} = MIN,$ $I_{OL} = 100 \text{ mA}$	V _{IL} = 0.8 V,		0.25	0.5		0.25	0.4	٧
VOL	Low-level output voltage	V _{CC} = MIN, I _{OL} = 300 mA	V _{IL} = 0.8 V,		0.5	0.8		0.5	0.7	
ЮН	High-level output current	$V_{CC} = MIN,$ $V_{OH} = 30 V$	V _{IH} = MIN,			300			100	μА
lį	Input current at maximum input voltage	$V_{CC} = MAX$,	V _I = 5.5 V			1			1	mA
ΊΗ	High-level input current	$V_{CC} = MAX,$	V _I = 2.4 V			40			40	μΑ
I _{IL}	Low-level input current	$V_{CC} = MAX$,	V _I = 0.4 V		-1	-1.6		-1	-1.6	mA
Іссн	Supply current, outputs high	$V_{CC} = MAX$,	V _I = 5 V		8	11		8	11	mA
ICCL	Supply current, outputs low	$V_{CC} = MAX$,	V _I = 0		54	68		54	68	mA

[‡] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER	TEST CO	NDITIONS	MIN	TYP	MAX	UNIT	
tPLH	Propagation delay time, low-to-high-level				18	25		
tPHL	Propagation delay time, high-to-low-level	I _O ≈ 200 mA,	$C_L = 15 pF$,		18	25	ns	
tTLH	Transition time, low-to-high-level output	$R_L = 50 \Omega$,	See Figure 1		5	8	115	
tTHL	Transition time, high-to-low-level output				7	12		
Va	High-level output voltage after switching	SN55453B	V _S = 20 V,	I _O ≈ 300 mA,		V _S -6.5		mV
VOH High-level output voltage after switching		SN75453B	See Figure 2		V _S −6.5			IIIV

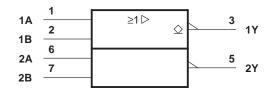


[§] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

SN55451B, SN55452B, SN55453B, SN55454B SN75451B, SN75452B, SN75453B, SN75454B DUAL PERIPHERAL DRIVERS

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logic symbol†



[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC publication 617-12.

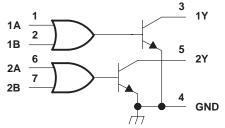
Pin numbers shown are for the D, JG, and P packages.

FUNCTION TABLE (each driver)

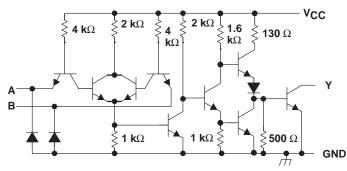
Α	В	Y
L	L	H (off state)
L	Н	L (on state)
Н	L	L (on state)
Н	Н	L (on state)

positive logic: Y = A+B or AB

logic diagram (positive logic)



schematic (each driver)



Resistor values shown are nominal.

electrical characteristics over recommended operating free-air temperature range

	PARAMETER	TEST COM	TEST CONDITIONS‡		SN55454B			SN75454B		
FARAMETER		1E31 CONDITIONS+		MIN	TYP§	MAX	MIN	TYP§	MAX	UNIT
٧ıĸ	Input clamp voltage	$V_{CC} = MIN,$	$I_{ } = -12 \text{ mA}$		-1.2	-1.5		-1.2	-1.5	V
\/a:	Low-level output voltage	V _{CC} = MIN, I _{OL} = 100 mA	V _{IH} = MIN,		0.25	0.5		0.25	0.4	٧
VOL		V _{CC} = MIN, I _{OL} = 300 mA	V _{IH} = MIN,		0.5	0.8		0.5	0.7	V
ЮН	High-level output current	V _{CC} = MIN, V _{OH} = 30 V	V _{IL} = 0.8 V,			300			100	μΑ
II	Input current at maximum input voltage	$V_{CC} = MAX$,	V _I = 5.5 V			1			1	mA
lιΗ	High-level input current	$V_{CC} = MAX$,	V _I = 2.4 V			40			40	μΑ
IլL	Low-level input current	$V_{CC} = MAX$,	V _I = 0.4 V		-1	-1.6		-1	-1.6	mA
ICCH	Supply current, outputs high	$V_{CC} = MAX$,	V _I = 0		13	17		13	17	mA
ICCL	Supply current, outputs low	$V_{CC} = MAX$,	V _I = 5 V		61	79		61	79	mA

[‡] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

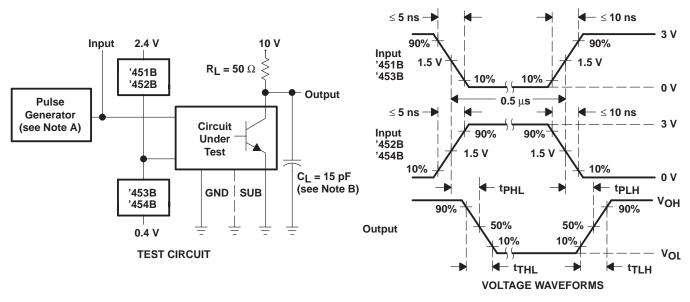
switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT	
tPLH	Propagation delay time, low-to-high-level output					27	35	
tPHL	Propagation delay time, high-to-low-level output		I _O ≈ 200 mA,	C _L = 15 pF,		24	35	ns
tTLH	Transition time, low-to-high-level output	$R_L = 50 \Omega$,	See Figure 1		5	8	115	
tTHL	Transition time, high-to-low-level output				7	12		
VOH High-level output voltage after switching		SN55454B	V _S = 20 V,	I _O ≈ 300 mA,		V _S -6.5		mV
VOH	nigh-level output voltage after switching	SN75454B	See Figure 2		V _S -6.5			IIIV



[§] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

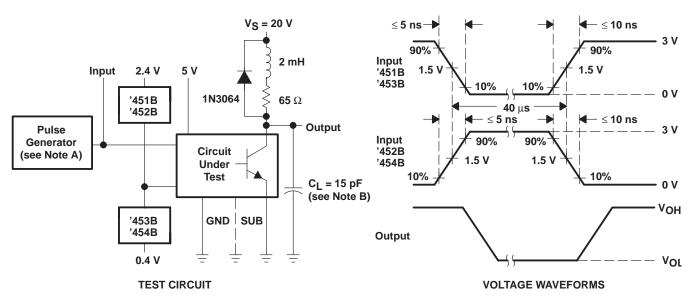
PARAMETER MEASUREMENT INFORMATION



NOTES: A. The pulse generator has the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω .

B. C_L includes probe and jig capacitance.

Figure 1. Test Circuit and Voltage Waveforms, Complete Drivers



NOTES: A. The pulse generator has the following characteristics: PRR \leq 12.5 kHz, Z_O = 50 Ω .

B. C_L includes probe and jig capacitance.

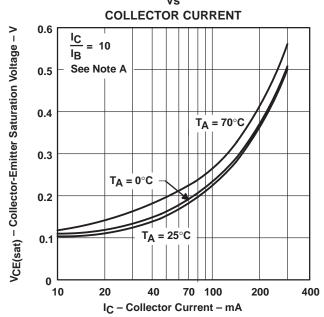
Figure 2. Test Circuit and Voltage Waveforms for Latch-Up Test of Complete Drivers



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TYPICAL CHARACTERISTICS

TRANSISTOR COLLECTOR-EMITTER SATURATION VOLTAGE



NOTE A: These parameters must be measured using pulse techniques, $t_{\text{W}}=300~\mu\text{s},$ duty cycle $\leq 2\%.$

Figure 3







12-Jan-2006

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9563301Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9563301QPA	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
77049012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
7704901PA	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
77049022A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
7704902PA	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/12902BPA	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/12903BPA	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/12905BPA	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
SN55451BJG	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
SN55452BJG	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
SN55453BJG	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
SN55454BJG	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
SN75451BD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75451BDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75451BDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75451BDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75451BP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75451BPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75451BPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75451BPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75452BD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75452BDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75452BDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75452BDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75452BP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75452BPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75452BPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75452BPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75453BD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM



PACKAGE OPTION ADDENDUM

12-Jan-2006

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN75453BDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75453BDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75453BDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75453BP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75453BPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75453BPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75453BPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75454BD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75454BDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75454BDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75454BDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75454BP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75454BPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75454BPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75454BPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ55451BFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ55451BJG	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ55452BFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ55452BJG	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ55453BFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ55453BJG	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ55454BFK	OBSOLETE	LCCC	FK	20		TBD	POST-PLATE	N / A for Pkg Type
SNJ55454BJG	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

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at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

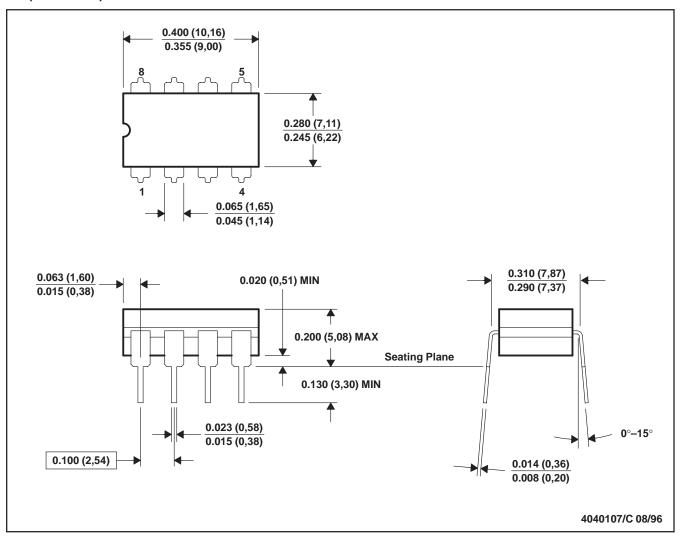
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

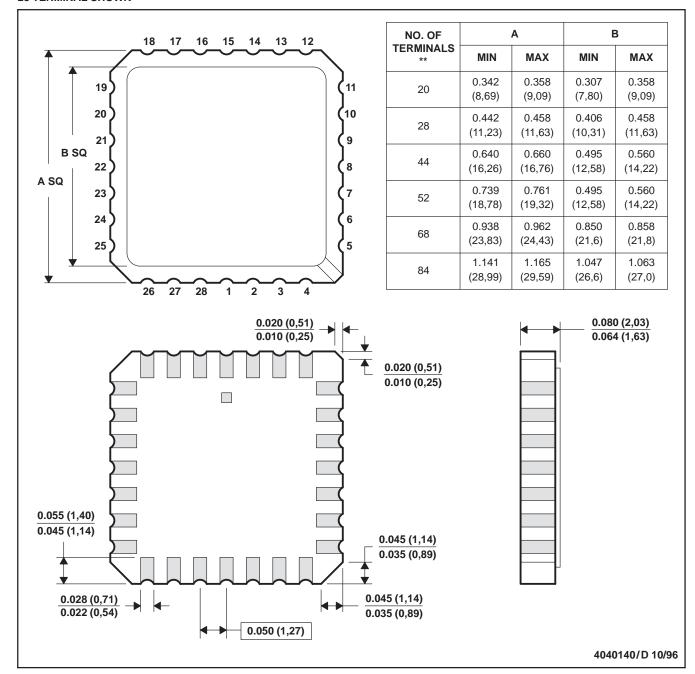
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T8



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER

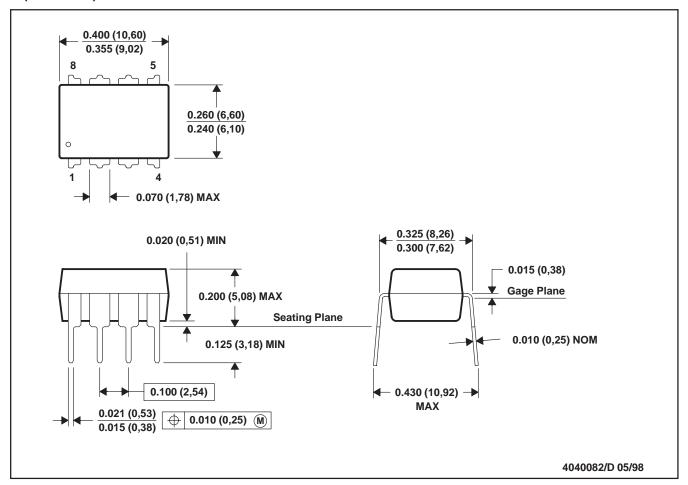


- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



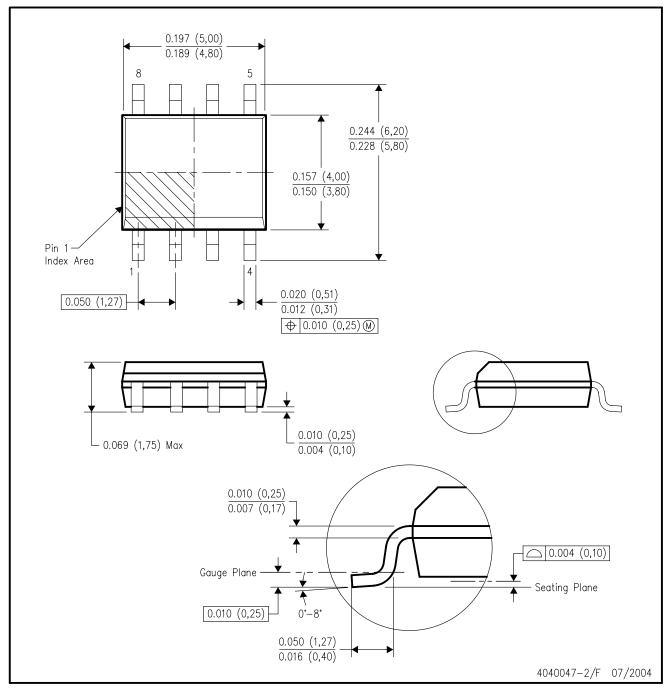
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001



D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

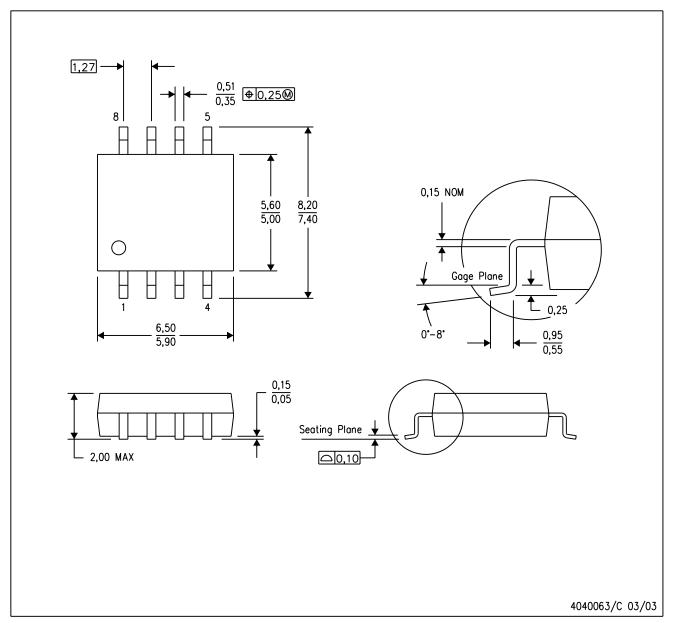
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AA.



MECHANICAL DATA

PS (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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